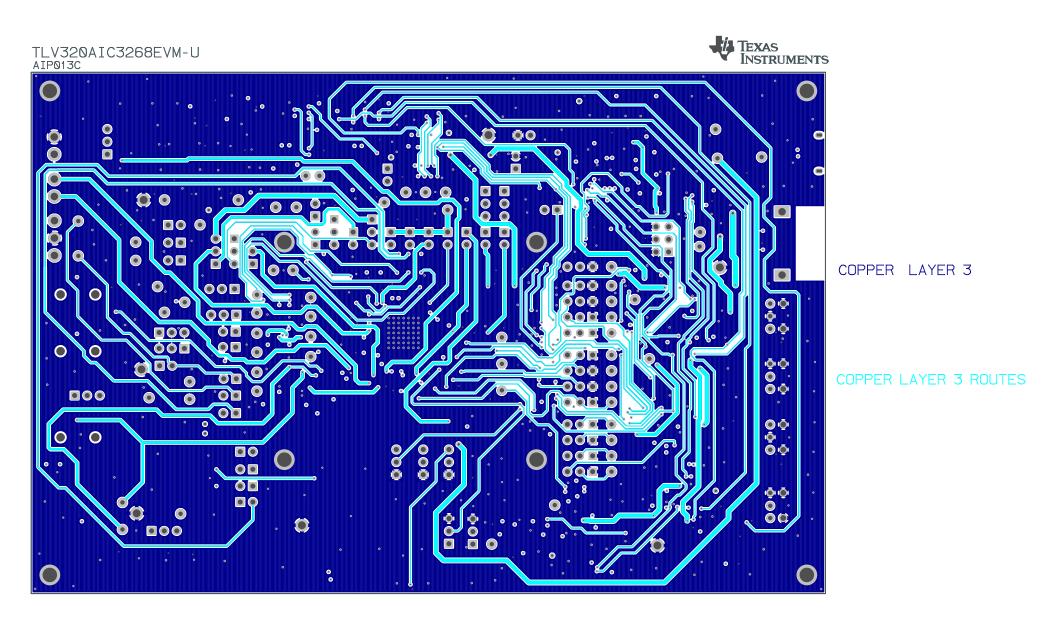
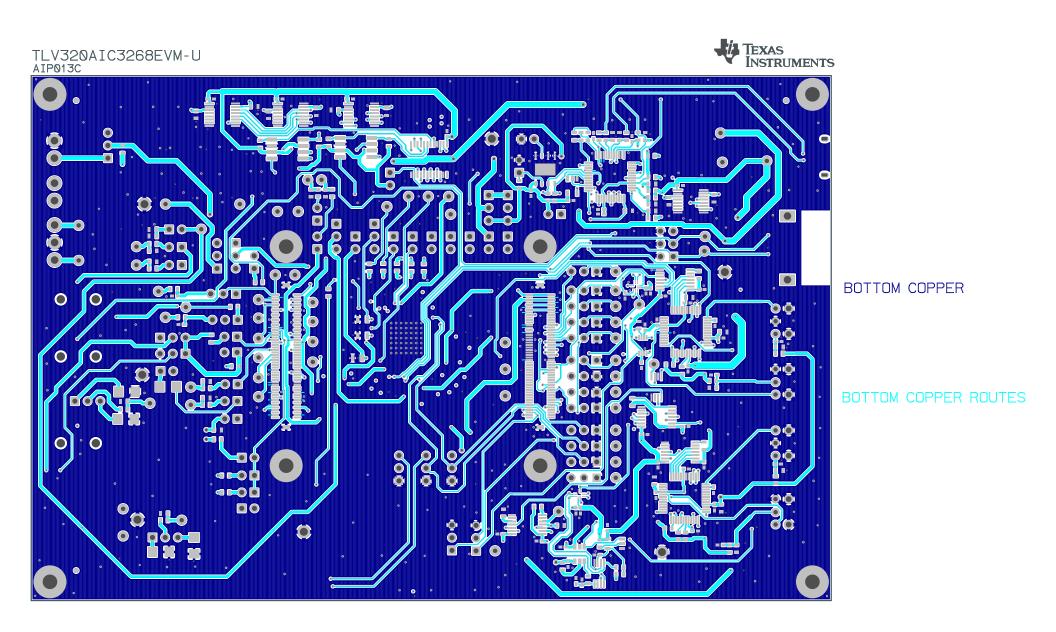
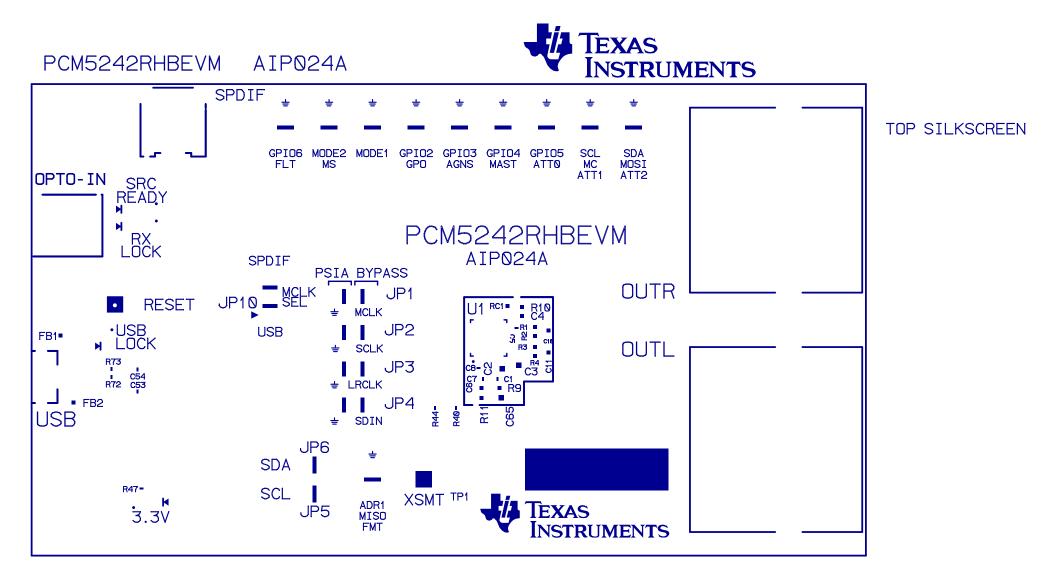
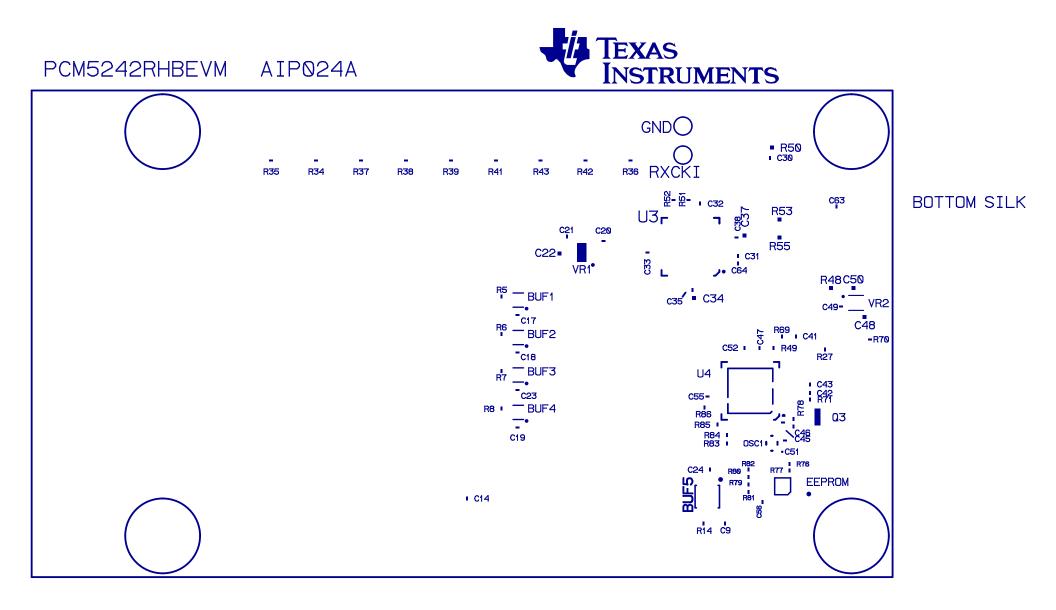


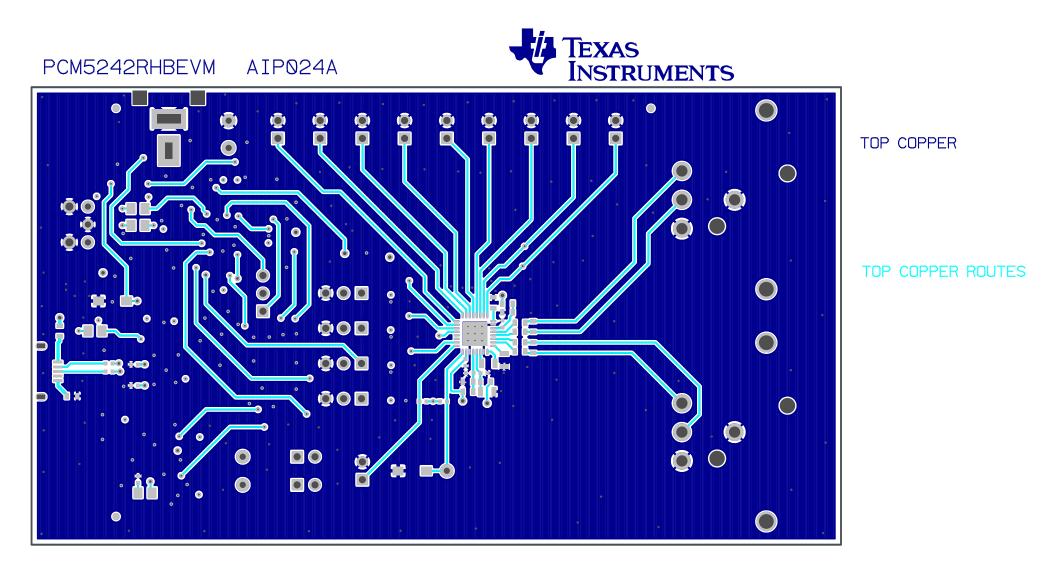
COPPER LAYER 2

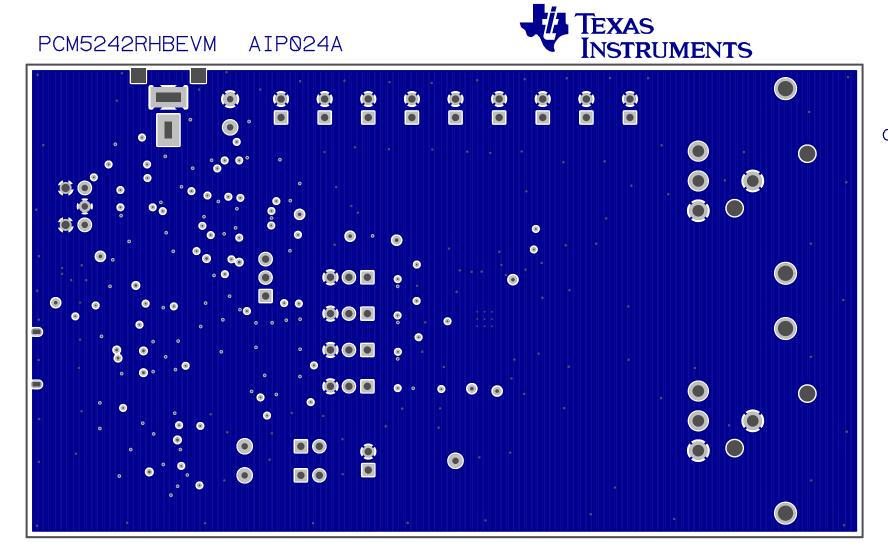




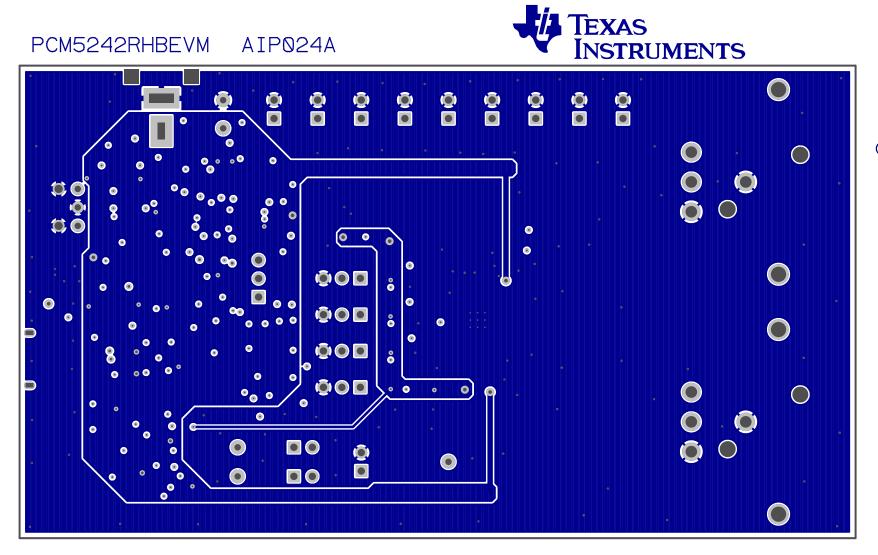




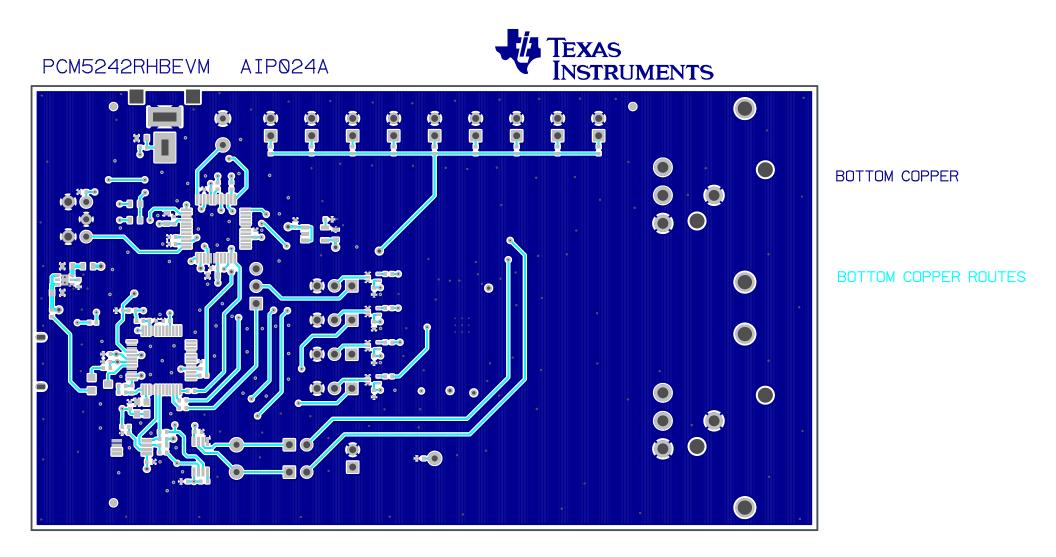


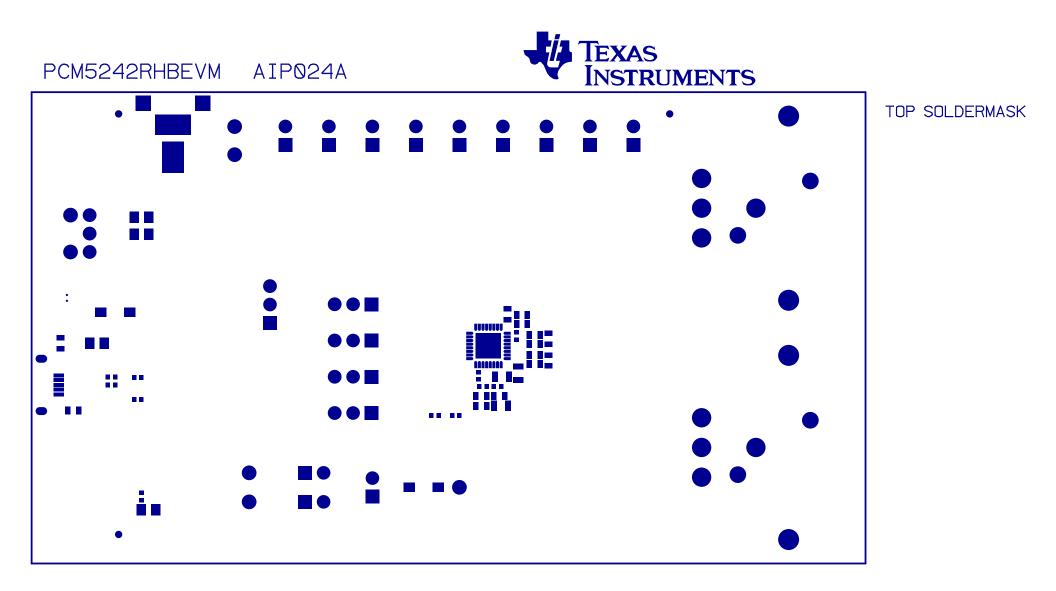


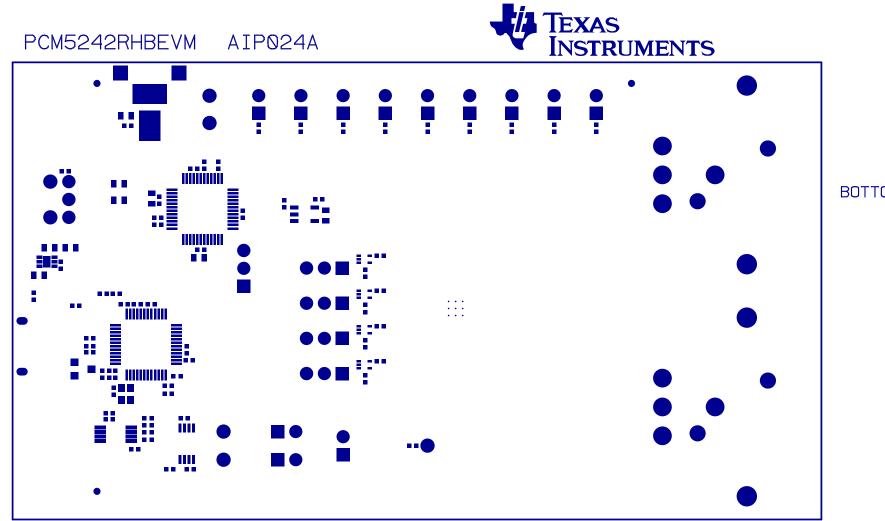
COPPER LAYER 2



COPPER LAYER 3

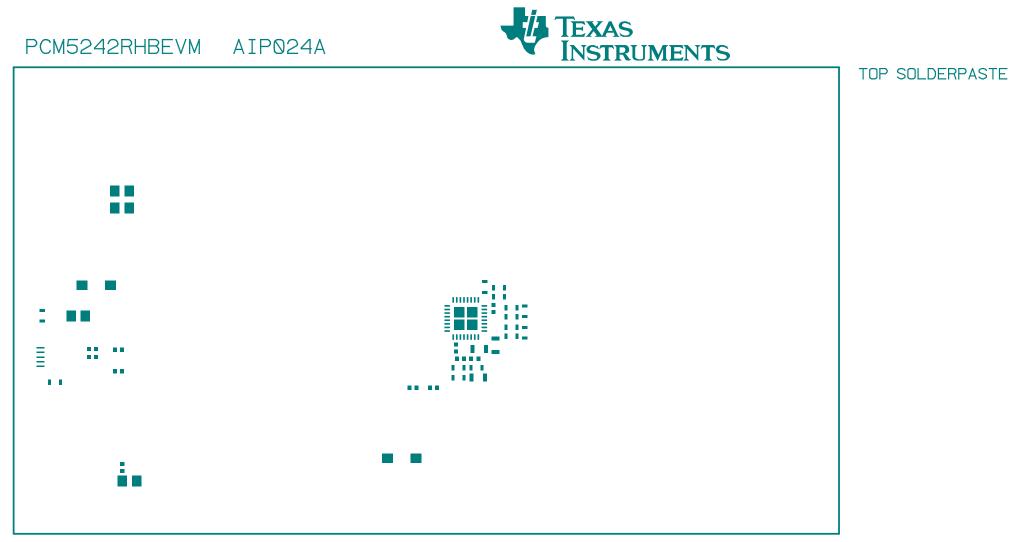


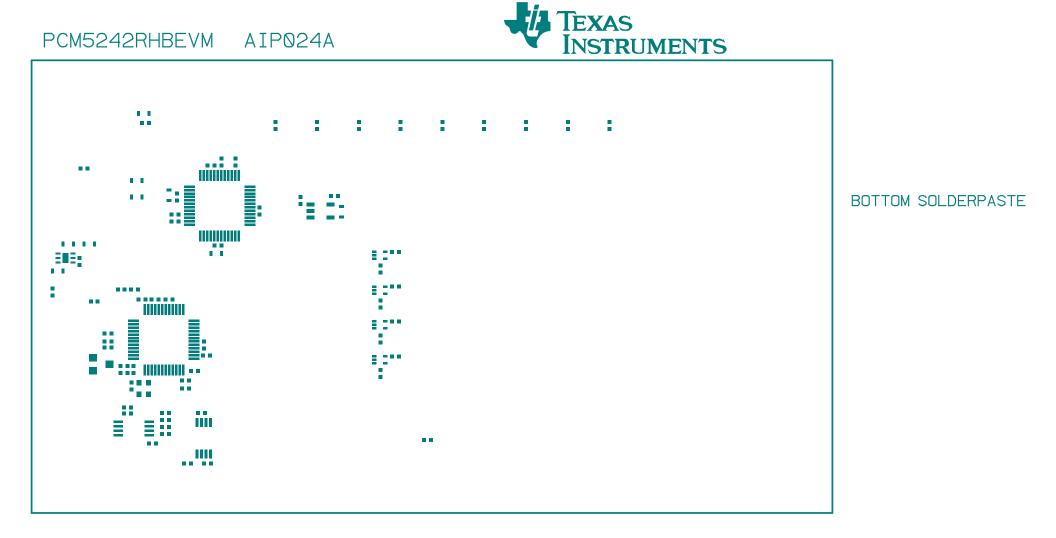


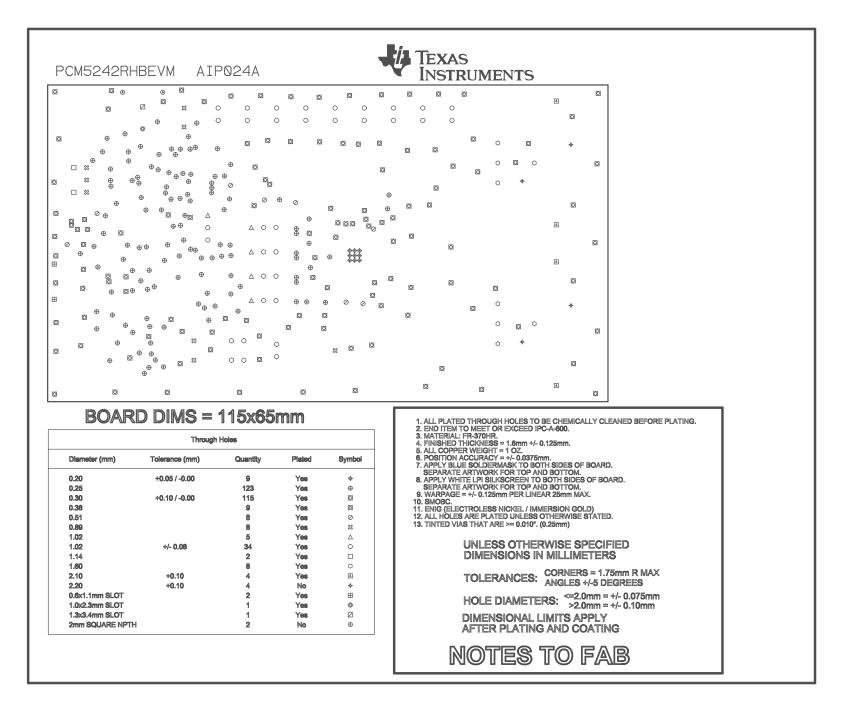


BOTTOM SOLDERMASK









TIDA-00403

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